

STN	Skúšobné metódy na elektrotechnické materiály, dosky s plošnými spojmi a iné spájacie štruktúry a zostavy Časť 2-809: Skúška koeficientu X/Y tepelnej rozťažnosti (CTE) pre hrubé základné materiály podľa TMA	STN EN IEC 61189-2-809 34 6513
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Test methods for electrical materials, circuit boards and other interconnection structures and assemblies - Part 2-809: X/Y coefficient of thermal expansion (CTE) test for thick base materials by TMA

Táto norma obsahuje anglickú verziu európskej normy.

This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 04/25

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EN IEC 61189-2-809

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English Version

**Test methods for electrical materials, circuit boards and other
interconnection structures and assemblies - Part 2-809: X/Y
coefficient of thermal expansion (CTE) test for thick base
materials by TMA
(IEC 61189-2-809:2024)**

Méthodes d'essai pour les matériaux électriques, les
circuits imprimés et autres structures d'interconnexion et
ensembles - Partie 2-809: Essai du coefficient de dilatation
thermique (CTE) X/Y pour matériaux de base épais à l'aide
d'un analyseur thermomécanique (TMA)
(IEC 61189-2-809:2024)

Prüfverfahren für Elektromaterialien, Leiterplatten und
andere Verbindungsstrukturen und Baugruppen - Teil 2-
809: Prüfung des X/Y-Wärmeausdehnungskoeffizienten
(CTE) für dicke Grundwerkstoffe mittels TMA
(IEC 61189-2-809:2024)

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Comité Européen de Normalisation Electrotechnique
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CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN IEC 61189-2-809:2025 (E)**European foreword**

The text of document 91/1983/FDIS, future edition 1 of IEC 61189-2-809, prepared by TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61189-2-809:2025.

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Annex ZA (normative)

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<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194-1	-	Printed boards design, manufacture and assembly - Vocabulary - Part 1: Common usage in printed board and electronic assembly technologies	-	-
IEC 60194-2	-	Printed boards design, manufacture and assembly - Vocabulary - Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies	-	-



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Edition 1.0 2024-12

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NORME INTERNATIONALE



Test methods for electrical materials, circuit boards and other interconnection structures and assemblies –

Part 2-809: X/Y coefficient of thermal expansion (CTE) test for thick base materials by TMA

Méthodes d'essai pour les matériaux électriques, les circuits imprimés et autres structures d'interconnexion et ensembles –

Partie 2-809: Essai du coefficient de dilatation thermique (CTE) X/Y pour matériaux de base épais à l'aide d'un analyseur thermomécanique (TMA)



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INTERNATIONAL STANDARD

NORME INTERNATIONALE



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Partie 2-809: Essai du coefficient de dilatation thermique (CTE) X/Y pour matériaux de base épais à l'aide d'un analyseur thermomécanique (TMA)**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**TEST METHODS FOR ELECTRICAL MATERIALS, CIRCUIT BOARDS AND
OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –****Part 2-809: X/Y coefficient of thermal expansion (CTE) test
for thick base materials by TMA**

FOREWORD

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Draft	Report on voting
91/1983/FDIS	91/1994/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

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TEST METHODS FOR ELECTRICAL MATERIALS, CIRCUIT BOARDS AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 2-809: X/Y coefficient of thermal expansion (CTE) test for thick base materials by TMA

1 Scope

This part of IEC 61189 defines the method to be followed for the determination of the X/Y coefficient of thermal expansion of electrical insulating materials by the use of a thermomechanical analyser (TMA).

This method is applicable to materials that are solid of the entire range of temperature used and retain sufficient hardness and rigidity over the temperature range so that irreversible indentation of the specimen by the sensing probe does not occur.

2 Normative references

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